MOSFET – Power, Single, P-Channel, Trench, ESD Protected, SC-88

12 V, 3.3 A

Features

- Leading Trench Technology for Low R_{DS(ON)} Extending Battery Life
- SC-88 Small Outline (2x2 mm, SC70-6 Equivalent)
- Gate Diodes for ESD Protection
- NV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- High Side Load Switch
- Cell Phones, Computing, Digital Cameras, MP3s and PDAs

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Param	Symbol	Value	Units			
Drain-to-Source Voltage	V_{DSS}	-12	V			
Gate-to-Source Voltage	V _{GS}	±12	V			
Continuous Drain	Steady	T _A = 25 °C	I _D	-2.7	Α	
Current (Note 1)	State	T _A = 85 °C		-2.0		
t ≤ 5 s		T _A = 25 °C		-3.3		
Power Dissipation Steady (Note 1) State		T _A = 25 °C	P _D	0.625	W	
Pulsed Drain Current	I _{DM}	-8.0	Α			
Operating Junction and S	T _J , T _{STG}	–55 to 150	°C			
Source Current (Body Di	Is	-0.8	Α			
Lead Temperature for So (1/8" from case for 10		ırposes	T_L	260	°C	

THERMAL RESISTANCE RATINGS (Note 1)

Parameter	Symbol	Max	Units
Junction-to-Ambient - Steady State	$R_{\theta JA}$	200	°C/W
Junction-to-Ambient - t ≤ 5 s	$R_{\theta JA}$	141	
Junction-to-Lead - Steady State	$R_{\theta JL}$	102	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

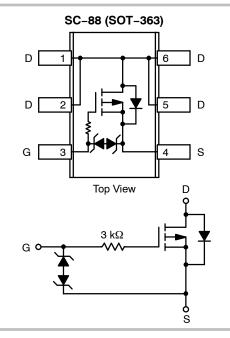
1. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).



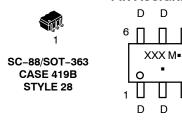
ON Semiconductor®

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V _{(BR)DSS}	R _{DS(on)} Typ	I _D Max
	45 m Ω @ –4.5 V	
-12 V	67 mΩ @ -2.5 V	-3.3 A
	133 mΩ @ –1.8 V	



MARKING DIAGRAM & PIN ASSIGNMENT



XXX = Device Code
M = Date Code
Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J=25°C unless otherwise stated)

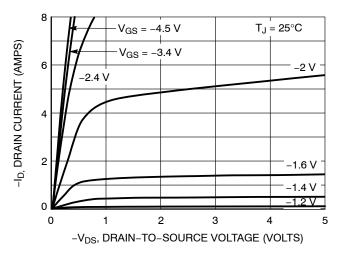
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-12			٧
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				10		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = -9.6 V, V _{DS} = 0 V	$T_{J} = 25^{\circ}C$ $T_{.J} = 125^{\circ}C$		-2.5	-1.0	μΑ
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _G	ľ		-2.5	±1.5	μΑ
date to course Loundge current	'GSS	$V_{DS} = 0 \text{ V}, \text{ V}_{G}$	_			±1.0	mΑ
ON CHARACTERISTICS (Note 2)		<i>D3</i> , c	10				
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D) = 100 μΑ	-0.40		-1.2	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J		,		3.4		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = -4.5 \text{ V},$	I _D = -3.3 A		45	60	mΩ
		$V_{GS} = -2.5 \text{ V}, I_D = -2.9 \text{ A}$ $V_{GS} = -1.8 \text{ V}, I_D = -1.0 \text{ A}$			67	90	
					133	160	
Forward Transconductance	9FS	$V_{GS} = -10 \text{ V}, I_D = -3.3 \text{ A}$			15		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}				850		pF
Output Capacitance	C _{OSS}	V _{GS} = 0 V, f = V _{DS} = -	1.0 MHz, 12 V		170		
Reverse Transfer Capacitance	C _{RSS}	- 53			110		
Total Gate Charge	Q _{G(TOT)}				8.6		nC
Gate-to-Source Charge	Q_{GS}	$V_{GS} = -4.5 \text{ V, V}$ $I_{D} = -3.5 \text{ V}$	_{DS} = -5.0 V, .3 A		1.3		
Gate-to-Drain Charge	Q_{GD}	נ			2.2		
Gate Resistance	R_{G}				3000		Ω
SWITCHING CHARACTERISTICS (No	te 3)						
Turn-On Delay Time	t _{d(ON)}	V_{GS} = -4.5 V, V_{DD} = -6.0 V, I_{D} = -1.0 A, R_{G} = 6.0 Ω			0.86		μs
Rise Time	t _r				1.5		
Turn-Off Delay Time	t _{d(OFF)}				3.5		
Fall Time	t _f				3.9		
DRAIN-SOURCE DIODE CHARACTE	RISTICS (Note 2	2)					
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		-0.85	-1.2	V
		$I_S = -3.3 \text{ A}$	T _J = 125°C		-0.7		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics for the listed test conditions.

2. Pulse Test: pulse width ≤ 300μs, duty cycle ≤ 2%.

3. Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)



8 V_{DS} ≤ -12 V

4 125°C

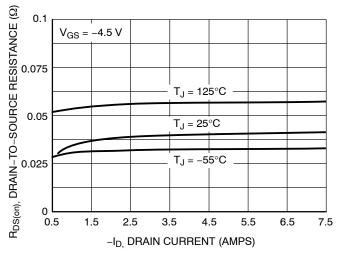
125°C

0 0.5 1 1.5 2 2.5 3 3.5 4 4.5

-V_{GS}, GATE-TO-SOURCE VOLTAGE (VOLTS)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



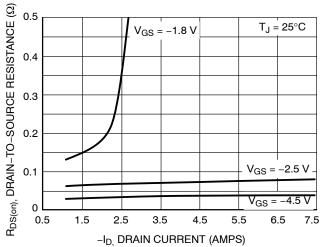


Figure 3. On–Resistance vs. Drain Current and Temperature

Figure 4. On-Resistance vs. Drain Current and Gate Voltage

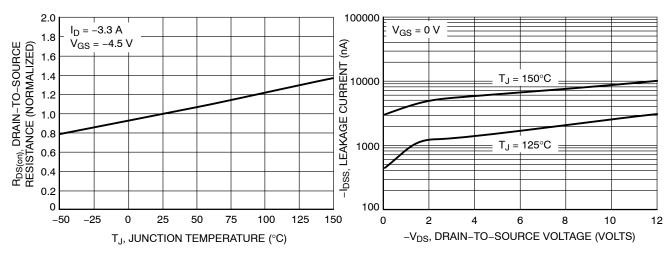
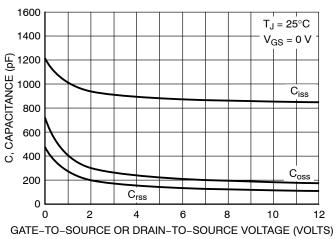


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)



-V_{GS,} GATE-TO-SOURCE VOLTAGE (VOLTS) 4.5 QT 3.5 3 2.5 2 Q2 1.5 1 $I_D = -3.3 A$ 0.5 T_J = 25°C 0 6 8 10 0 Q_a, TOTAL GATE CHARGE (nC)

Figure 7. Capacitance Variation

Figure 8. Gate-to-Source Voltage vs. Total Gate Charge

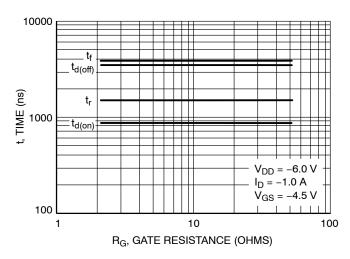


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

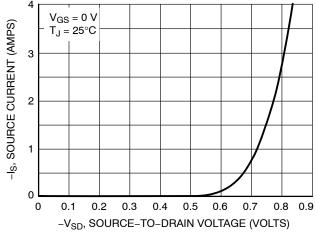


Figure 10. Diode Forward Voltage vs. Current

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTJS3151PT1G	TJ		
NTJS3151PT2G	TJ	SC-88 (Pb-Free)	3000 / Tape & Reel
NVJS3151PT1G*	VTJ	, ,	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**

DATE 11 DEC 2012





NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H. DATUMS A AND B ARE DETERMINED AT DATUM H. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.

- DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MILLIMETERS				INCHES	}
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10			0.043
A1	0.00		0.10	0.000		0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
E	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65 BSC			0	.026 BS	С
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC 0.006 BSC				SC	
aaa	0.15				0.006	
bbb	0.30				0.012	
ccc	0.10				0.004	
ddd		0.10			0.004	

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

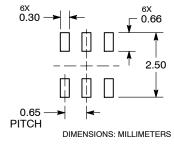
= Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

- *Date Code orientation and/or position may vary depending upon manufacturing location.
- *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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DATE 11 DEC 2012

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
STYLE 19: PIN 1. I OUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 25: PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 27: PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 29: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE/ANODE 6. CATHODE	STYLE 30: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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